

DiskOnChip Lead-Free Products



Description

M-Systems is announcing the availability of its lead-free DiskOnChip product line.

Ordering Information and Availability

Table 1 lists both lead-free and currently available, standard DiskOnChip products. It also provides a schedule for the availability of lead-free DiskOnChip products. Both product lines will be offered in parallel.

Table 1: Current and Lead-Free DiskOnChip Products

Capacity		Package	Ordering Information, Current Non Lead-Free DiskOnChip Product	Lead-Free DiskOnChip Product		
Mbit	MByte			Ordering Information	Availability	
					Engineering Samples	Mass Production
128	16	TSOP-I	MD2811-D16-V3Q18	MD2811-D16-V3Q18-P	7/2002	8/2002
256	32	TSOP-I	MD2811-D32-V3	MD2811-D32-V3-P	5/2002	7/2002
256	32	BGA 9X12	MD3831-D32-V3	MD3831-D32-V3-P	Q4/2002	Q2/2003
512	64	BGA 9X12	MD3331-D64-V3	MD3331-D64-V3-P	Q4/2002	Q2/2003

Lead-Free Composition

The lead-free plating on the pins for the TSOP package will be manufactured from SnCu.

The lead-free balls for the BGA package will be manufactured from SnAgCu.

Reflow Profile

Figure 1 shows a recommended example of temperature profiles for infrared or convection reflow for lead-free solders.

The maximum temperature during mounting processes is 260°C, and the minimum is 230°C. The process should take between 30-50 seconds.

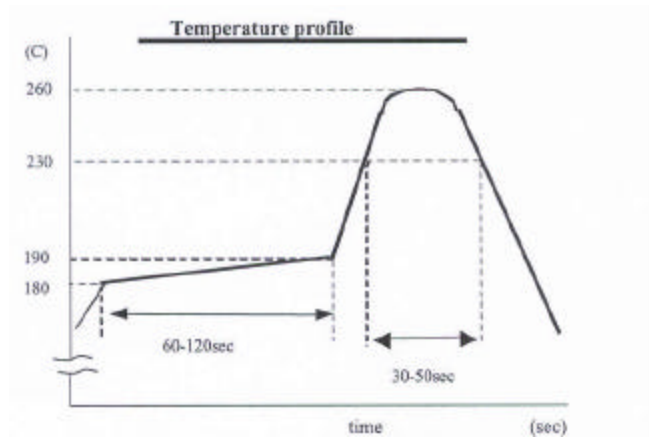


Figure 1: Recommended Reflow Profile

Solder heat-resistance varies between products. The temperature profile above shows maximum guaranteed device temperature based on a typical condition of solder reflow. Set the optimal temperature profile conditions within the recommended profile above and according to the material and the solder paste, as well as the product characteristics.

How to Contact Us

Please contact your M-Systems' representative or visit the DiskOnChip web page on M-Systems web site (www.m-sys.com) for any further information or assistance.

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